



A4375

REVISIONS					
SYM	DESCRIPTION	DATE	E.M.N. NO.	DRAFT	CHKD APPD
X	EXPERIMENTAL RELEASE	6.21.66	-	WTD	CB
Q	ORIGINAL RELEASE FOR PRODUCTION	7.19.66	Q	RME	

ASSEMBLY NOTES

1. TO MOUNT COMPONENTS INSERT LEAD THROUGH PLATED-THRU HOLES.
2. APPLY HEAT AND SOLDER TO LEAD & FOIL. CAUTION: TO MUCH HEAT WILL CAUSE THE FOIL TO SEPARATE FROM THE BOARD.
3. CLEAN AND INSPECT PER S676.
4. FUNGUS PROOFING PER TMC SPECIFICATION S113.
5. BOARD EDGES MUST BE CLEARED OF SOLDER. APPROXIMATELY 3/16 FROM EDGES.

REF: CK1148

REQ'D.	ITEM	PART NUMBER	DESCRIPTION	SYMBOL
	6	BS100	SOLDER TIN ALLOY	
1	5	NW108-29	AND GATE	Z15
4	4	NW108-28	AND GATE	Z4, 5, 6, 8
4	3	NW107-4X	FLIP FLOP	Z1, 2, 3, 7,
6	2	NW120-11	EMITTER FOLLOWER	Z6 THRU Z14
	1	PC256	PRINTED CIRCUIT BOARD	

EATON		LIST OF MATERIAL			
MATERIAL		THE TECHNICAL MATERIEL CORP. MAMARONECK, NEW YORK			
FINISH		TITLE ASS'Y PRINTED CIRCUIT BD (MEMORY/GATING CIRCUIT)			
UNLESS OTHERWISE SPECIFIED DIMENSIONS ARE IN INCHES AND INCLUDE CHEMICALLY APPLIED OR PLATED FINISHES		DRAWN WTD	DATE 6.9.66	FINAL APPROVAL	
		CHECKED CB	DATE	7/19/66	
DECIMALS .X ± .05 .XX ± .01 .XXX ± .005		ELECT. DES.	DATE	A4375	
FRACTIONS ± 1/64 ANGLES ± 0° 30'		MECH. DES.	DATE	REV. LTR.	
TOLERANCES		SHEET		REV. LTR.	

HOLES SHOWN FOR COMPONENT MOUNTING, USED FOR REFERENCE ONLY.

5	RTIH-1	
Q'TY./UNIT	MODEL USED ON	ASS'Y. NO.
SCALE 2/1	CODE	
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